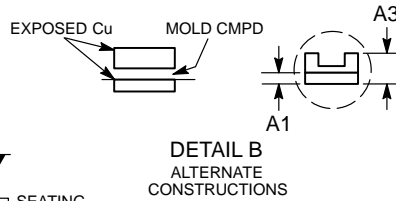
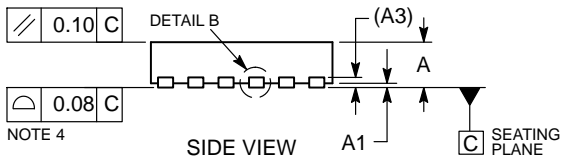
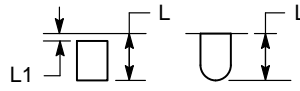
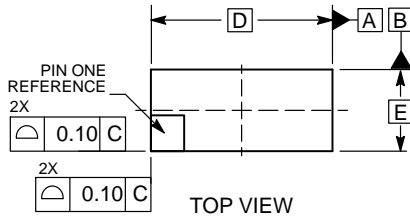


WDFN12, 3x1.35, 0.5P  
CASE 511AZ i01  
ISSUE O

12

DATE 16 JUL 2010

1  
SCALE 4:1

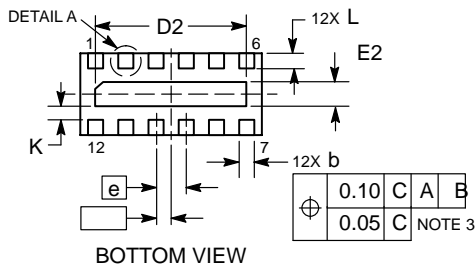


NOTES:

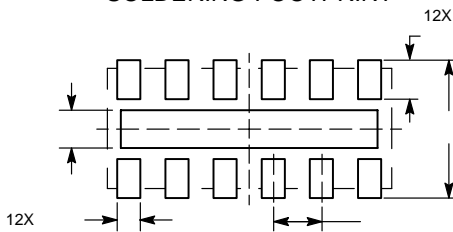
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.70	0.80
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	3.00	BSC
D2	2.40	2.60
E	1.35	BSC
E2	0.30	0.50
e	0.50	BSC

L	0.20	0.30
L1	0.15	0.15



RECOMMENDED  
SOLDERING FOOTPRINT\*



DIMENSION: MILLIMETERS

\*For additional information on our Pb iFree strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.